



ON Semiconductor®

# STORMWATER POLLUTION PREVENTION PLAN ON SEMICONDUCTOR POCATELLO, IDAHO

## Table of Contents

- 1.0 INTRODUCTION .....2
  - 1.1 Regulatory Framework.....2
  - 1.2 Plan Objectives .....2
  - 1.3 Required Contents of this SWPPP .....2
  - 1.4 SWPPP Modifications.....3
  - 1.5 SWPPP Availability .....3
  - 1.6 Plan Retention and Availability .....3
  - 1.7 Plan Requirements .....3
- 2.0 FACILITY INFORMATION .....4
  - 2.1 Site Description.....4
  - 2.2 Regional and Site Geologic Conditions .....5
  - 2.3 Site Drainage Information.....5
  - 2.4 Site Security and Safety .....5
  - 2.5 Stormwater Pollution Prevention Team .....6
  - 2.6 List of Significant Spills or Leaks of Toxic or Hazardous Pollutants to Stormwater.....6
  - 2.7 Unauthorized Non-Stormwater Discharges .....6
- 3.0 POTENTIAL POLLUTANTS .....7
  - 3.1 Summary of Potential Pollutant Sources On-site .....8
  - 3.2 List of Potential Pollutants.....10
  - 3.3 Salt Storage.....10
  - 3.4 Sampling Data .....11
- 4.0 STORMWATER POLLUTION CONTROLS .....11
  - 4.1 Stormwater Management .....11
    - 4.1.1 Operational BMPs .....11
    - 4.1.2 Source Control BMPs .....12
    - 4.1.3 Recommended BMPs .....13
  - 4.2 Spill Prevention Response Procedures .....15
  - 4.3 Preventive Maintenance .....15
    - 4.3.1 Stormwater Drainage System Maintenance .....15
    - 4.3.2 Inspections .....15
    - 4.3.3 Good Housekeeping.....16
    - 4.3.4 Facility Maintenance.....16
    - 4.3.5 Erosion and Sediment Controls .....16
  - 4.4 Employee Education .....16
- 5.0 Inspections, Recordkeeping, and Internal Reporting Procedures .....17
  - 5.1 Records Requirements .....19
- 6.0 DOCUMENTATION TO SUPPORT ELIGIBILITY CONSIDERATIONS UNDER OTHER FEDERAL LAWS 20
  - 6.1 Documentation Regarding Endangered and Threatened Species and Critical Habitat Protection .....20
  - 6.2 Documentation Regarding Historic Properties Preservation.....20
- 7.0 PLAN CERTIFICATION.....20
- Appendix 1 – Figures and Maps .....22
- Appendix 2 – ASPP and Chemical Spill Response Procedure .....24
- Appendix 3 - QUARTERLY ROUTINE STORMWATER INSPECTION FORM .....41
- Appendix 4 - QUARTERLY VISUAL ASSESSMENT FORM.....42
- Appendix 5 – Documentation Regarding Endangered and Threatened Species and Critical Habitat Protection .....43
- Appendix 6 – Documentation Regarding Historic Properties Preservation.....48

## **1.0 INTRODUCTION**

This Stormwater Pollution Control Plan (SWPPP) has been prepared for ON Semiconductor in Pocatello, Idaho to meet the requirements of the Environmental Protection Agency's (EPA) stormwater quality protection programs.

### **1.1 Regulatory Framework**

In order to reduce the impact to water quality from pollutants contained in stormwater runoff, on November 16, 1990, Congress issued an amendment to the Clean Water Act, which required the EPA to control stormwater discharges through implementation of the National Pollutant Discharge Elimination System (NPDES) permit program. EPA's stormwater permit program is codified in Title 40 of the Code of Federal Regulations (CFR) Part 122. The 2015 Multi-Sector General Permit for Stormwater Discharges Associated with Industrial Activity (MSGP) was developed by EPA to address stormwater for industrial facilities.

### **1.2 Plan Objectives**

ON Semiconductor is committed to conducting business in an environmentally responsible manner. This includes taking appropriate measures to minimize the potential for stormwater containing significant amounts of pollutants from discharging to surface waters. Accordingly, we have developed the following SWPPP. The primary objectives of this SWPPP are to:

- 1) Eliminate the discharge of process wastewater, domestic wastewater, and non-contact cooling water to stormwater drainage systems
- 2) Implement Best Management Practices (BMPs) that will identify the sources of stormwater pollution and reduce or eliminate the discharge of stormwater pollutants
- 3) Prevent violations of surface water quality, groundwater quality, and sediment management standards
- 4) Minimize peak rates and volumes of stormwater to prevent adverse water quality impacts including beneficial uses of the receiving water

In order to achieve these objectives, ON Semiconductor has adopted the EPA's listed content requirements in development of this SWPPP.

### **1.3 Required Contents of this SWPPP**

For coverage under the 2015 MSGP, the following SWPPP elements are required:

- Stormwater pollution prevention team
- Site description
- Summary of potential pollutant sources
- Description of control measures
- Schedules and procedures
- Documentation to support eligibility considerations under other federal laws

- Signature requirements

The specific required details for each section are outlined in the 2015 MSGP in Part 5.

#### **1.4 SWPPP Modifications**

This SWPPP must be modified based on the corrective actions and deadlines required under Part 4.3 and that were documented under Part 4.4 of the 2015 MSGP. SWPPP modifications must be signed and dated in accordance with Appendix B, Subsection 11. To meet a corporate requirement, the SWPPP will be reviewed annually. Review will be documented in the Revision History table at the end of the Plan.

#### **1.5 SWPPP Availability**

A complete copy of the current SWPPP is retained at the Pocatello facility and includes all documents incorporated by reference and all documentation supporting permit eligibility pursuant to Part 1.1 of the 2015 MSGP, as well as the signed and dated certification page. The SWPPP will be immediately available to facility employees, EPA, the State of Idaho, and representatives of the U.S. Fish and Wildlife Service (USFWS) at the time of an onsite inspection. The required elements of this SWPPP are available to the public via posting on the internet.

#### **1.6 Plan Retention and Availability**

A current copy of the SWPPP shall be maintained in the Environmental Health and Safety Group (EHS) files.

#### **1.7 Plan Requirements**

Consistent with our overall approach and stated plan objectives, ON Semiconductor has incorporated the following elements into our SWPPP:

- Site Description, including:
  - a general location map showing the location of the site in relation to major transportation routes, surface waters, and other relevant features
  - a detailed site map showing point source discharges, stormwater drainage patterns and drainage areas, discharge structures, impervious surfaces, buildings, surface water bodies, etc.
  - a list of potential pollutants that are stored on site
  - identification of site locations used for storage or disposal of raw materials, fuels, solvents, degreasers, products, hazardous substances, fertilizers, pesticides; and waste products that may have the potential to commingle with the stormwater runoff.
- Stormwater Pollution Controls:
  - operational BMPs, source control BMPs, and other additional available and reasonable BMPs which include containment, debris

- and sediment controls, waste chemical disposal, stormwater diversion, and covered storage and manufacturing areas
  - spill prevention and response procedures
  - preventative maintenance program
  - employee awareness training
  - inspections, record keeping and internal reporting procedures
- Schedule for monitoring activities, applicable BMPs, and other activities identified in the SWPPP.

The remainder of the document addresses, in detail, each of the Plan requirements stated above.

## **2.0 FACILITY INFORMATION**

ON Semiconductor Pocatello is a semiconductor manufacturing facility with an eight inch wafer fab producing 0.35  $\mu\text{m}$  to 1.5  $\mu\text{m}$  analog complementary metal-oxide semiconductor (CMOS), BCD (bipolar CMOS DMOS) (diffused metal-oxide semiconductor), advanced discrete, and custom technologies for industrial, automotive, medical, etc. applications. The facility is located at 2300 Buckskin Road in Pocatello, Idaho; it was purchased from AMI Semiconductor on March 17, 2008. The general location is shown on Figure 1. The site stormwater system and sampling point are shown in Figure 2. The facility is bounded by Buckskin Road to the north; Franklin Middle School to the west; Idaho State University Business and Technology Research Park, the ON Semiconductor Engineering Research Center (ERC), and the Idaho Department of Health and Welfare office to the southeast; and undeveloped land belonging to Idaho State University to the south. The surrounding land use is primarily industrial, health services, and educational purposes. See Figure 1 for General Location Map.

### **2.1 Site Description**

The Pocatello manufacturing facility occupies the central portion of the site. The ERC occupies the upper portion of the site and is accessed from either Alvin Ricken Drive or a long, covered stairwell that connects to the lower portion of the facility. The footprint of the ON Semiconductor facility covers approximately 33 acres of land and consists of a manufacturing fab, a central processing building (primarily office space), a central utilities building, a chemical storage building, a smaller office building, a records retention building the ERC, and a wastewater treatment building. See Figure 2 for Site Map.

The majority of the site is impervious driveway, parking lot, and buildings. The area adjacent to the East property line is a slope covered with natural vegetation. The Southwest section of property is a lawn. There are no known sensitive environments within two miles of the facility. The nearest known sensitive environment is the Portneuf River, two miles from the facility.

## **2.2 Regional and Site Geologic Conditions**

The facility is located on a bench at the base of the Pocatello Mountain Range in the Portneuf Valley.

The regional geology consists of loess blanketed alluvial fan gravel of Wisconsin Age (late Pleistocene), crudely stratified muddy sand, and pebble-to-boulder gravel overlain by calcareous loess that together form the surface of the coalesced relict alluvial fans of the prominent "east" and "west" benches in Pocatello. Elevations, fan surface gradients, and soil evidence suggest the upper part of the alluvial fan gravel was deposited during the high stand of Pleistocene American Falls Lake during the Wisconsin glaciation. The Wisconsin alluvial fans were graded to the ancestral Portneuf River, which in turn was graded to the ancestral American Falls Lake, estimated to have been as high as 4,440-4,450 feet in elevation.

The alluvial fans were entrenched after the lake lowered prior to the Bonneville Flood. Soil evidence suggests the loess blanketed the fans in late Wisconsin time. The benches formed when the Bonneville Flood truncated the alluvial fan gravels and the loess. The loess is thickest on flatter slopes and absent on some south-facing slopes. Core drilling performed on both the east and west benches indicates the loess ranges in thickness from 1 to 6 meters (about 3 to 20 feet) and locally buries alluvial fan gravel by as much as 12 meters (40 feet).

## **2.3 Site Drainage Information**

The topography of the majority of the site shows ground sloping from East to West (Figure 2.0). Runoff from the developed areas of the site flows generally to the West and is diverted to the on-site stormwater collection system which drains to the stormwater retention pond located on the west side of the ON Semiconductor property, adjacent to Franklin Middle School. This 1/2-acre stormwater retention pond reduces the peak stormwater runoff from the site to a level lower than prior to the development. The pond was designed for a 100-year flood event, which also reduces the need for public flood control systems. Runoff from land belonging to Idaho State University and the City of Pocatello constitutes the majority of the water entering the stormwater retention pond.

## **2.4 Site Security and Safety**

Delivery access to the ON Semiconductor facility is controlled by security gates located at the Buckskin Road East and West entrances, which are controlled access points monitored by Security. Security personnel use video surveillance to monitor the facility.

Visitors to ON Semiconductor are required to sign in and obtain a visitor badge. Persons without authorization or identification are denied access. In addition to controlling access to the facility, the security officers' responsibilities include:

- Emergency Response Coordination
- Watching for fire
- Inspecting the facility for damage
- Deterring theft
- Monitoring visitors and contractors within the plant

## **2.5 Stormwater Pollution Prevention Team**

The Stormwater Pollution Prevention Team is directed by the site Environmental Engineer.

The team will consist of the EHS department, including the EHS Manager, Environmental Engineer, Safety Engineer, and EHS Technician. The Stormwater Pollution Prevention Team will be trained under the direction of the Environmental Engineer as necessary. The stormwater pollution prevention team is responsible for overseeing development of the SWPPP and any modifications to it and for implementing and maintaining control measures and taking corrective actions when required. The Environmental Engineer has primary responsibility for the SWPPP document maintenance.

## **2.6 List of Significant Spills or Leaks of Toxic or Hazardous Pollutants to Stormwater**

There have been no significant spills or leaks of oil or toxic or hazardous substances that occurred at exposed areas, or that drained to a stormwater conveyance, in the last three years (§5.2.3.3 2015 MSGP).

## **2.7 Unauthorized Non-Stormwater Discharges**

An evaluation was conducted on September 15, 2018, during a quarterly inspection, for the presence of unauthorized non-stormwater discharges. The evaluation criteria used included the list of Allowable Non-Stormwater Discharges for all Sectors of Industrial Activity from §1.1.3.1 of the 2015 MSGP.

### ***1.1.3.1 Allowable Non-Stormwater Discharges for all Sectors of Industrial Activity:***

- Discharges from emergency/unplanned fire-fighting activities
- Fire hydrant flushing
- Potable water, including water line flushing
- Uncontaminated condensate from air conditioners, coolers/chillers, and other compressors and from the outside storage of refrigerated gases or liquids
- Irrigation drainage
- Landscape watering provided all pesticides, herbicides, and fertilizers have been applied in accordance with the approved labeling

- Pavement wash waters where no detergents or hazardous cleaning products are used (e.g., bleach, hydrofluoric acid, muriatic acid, sodium hydroxide, nonylphenols), and the wash waters do not come into contact with oil and grease deposits, sources of pollutants associated with industrial activities (see Part 5.2.3), or any other toxic or hazardous materials, unless residues are first cleaned up using dry clean-up methods (e.g., applying absorbent materials and sweeping, using hydrophobic mops/rags) and you have implemented appropriate control measures to minimize discharges of mobilized solids and other pollutants (e.g., filtration, detention; settlement)
- Routine external building washdown / power wash water that does not use detergents or hazardous cleaning products (e.g., those containing bleach, hydrofluoric acid, muriatic acid, sodium hydroxide, nonylphenols)
- Uncontaminated ground water or spring water
- Foundation or footing drains where flows are not contaminated with process materials
- Incidental windblown mist from cooling towers that collects on rooftops or adjacent portions of your facility, but not intentional discharges from the cooling tower (e.g., “piped” cooling tower blowdown; drains)

A facility walk about was conducted and the outfall from the stormwater detention pond was directly observed during the evaluation. No actions were taken to eliminate unauthorized discharges because none were found. It should be noted that there has only been outfall from the stormwater detention pond twice in the last 30 years. Idaho precipitation levels and the size of the pond prohibit outfall.

### **3.0 POTENTIAL POLLUTANTS**

Listed below are sources of potential pollutants that are from sources external to ON Semiconductor; the pollutants can run onto ON Semiconductor property or into the stormwater system from outside sources. ON Semiconductor - Pocatello has no control over these properties' sources or their potential pollution sources. The major contributors have been contacted about their contribution to the stormwater system. Refer to Figure 1 for map. Note that there is only one outfall for this facility, the outfall from the stormwater detention pond. See Figure 2 for outfall location.

- North of Site
  - Buckskin Road – stormwater runoff from Buckskin Road upslope of the site drains into the ON Semiconductor stormwater system. The residences, medical building, and hospital all route their stormwater into the street; the stormwater is then collected in catch basins and is subsequently routed to the ON Semiconductor retention pond. Potential pollutants include road sand and sediment, snowmelt chemicals, automobile chemicals, leaking garbage dumpsters, and household and yard waste.
- East of Site

- There is a 36-inch culvert that routes all upslope runoff to the stormwater retention pond. This runoff includes stormwater from the Idaho Accelerator Center, a large area of land and lawns owned by Idaho State University, water from the City water tank discharge, and water from Alvin Ricken Drive and Buckskin Road. In addition, during a major storm event, the retention ponds/swales at the Engineering Research Building, the Idaho State University Technology and Business Park, and the Idaho Department of Health and Welfare may overflow, and stormwater could enter the ON Semiconductor stormwater system. Potential pollutants include road sediment, automobile chemicals, leaking garbage dumpsters, fertilizer, pesticide, sand and gravel from winter maintenance, and snow melt salt.
- In addition, the Idaho State University Technology and Business Park's stormwater pond percolates water into the ground that daylight in the ON Semiconductor East slope and is eroding the slope. The water runs down to a retaining wall and then either spills over the top of the wall or routes down the wall and discharges onto the driveway. In similar fashion, the Idaho Department of Health and Welfare stormwater pond water daylight farther down the East slope and is eroding the slope. These two run-on sources potentially could bring parking lot pollutants as well as anything else that is discharged to their respective stormwater systems.
- South of Site
  - The undeveloped land slopes away from the site and there is no risk of stormwater running onto the site.
- West of Site
  - The land slopes to the West and there is no risk of stormwater running onto the site

### 3.1 Summary of Potential Pollutant Sources On-site

The SWPPP must address all areas that are associated with industrial activities and that have been or may potentially be sources of significant amounts of stormwater pollutants. The following table briefly describes the areas at the Pocatello facility that are associated with industrial activity, identifies the materials that may be stored or used in those areas, and lists BMPs practiced to prevent stormwater discharges.

Area	Activity exposed to precipitation or surface runoff	Potential Pollutants	Best Management Practices and Control Measures
Chemical loading & unloading docks	Chemical and gas cylinder unloading	See List of Potential Pollutants	Sump valve is closed at all times. See Section 4.1.1. Spill response material located on dock.
Driveways	Transfer of chemicals from chemical warehouse to fab area	See List of Potential Pollutants	Follow procedure for transferring chemicals. See Section 4.1.1. Contact Emergency Response Team for incidents.

<b>Area</b>	<b>Activity exposed to precipitation or surface runoff</b>	<b>Potential Pollutants</b>	<b>Best Management Practices and Control Measures</b>
Material Roll-Off Bins	Storage of solid waste	Office and recyclable refuse	Quarterly inspections to ensure proper housekeeping. If dumping on the driveway is unpreventable, contain material and prohibit entrance to the stormwater system and/or place filter in the catch basin.
Parking lot and sidewalks	Sanding and snow melt during winter maintenance	Sand, snow melt chemicals	Store snow melt indoors or in covered locations. Apply as little sand and snow melt as possible. Sweep parking lot in spring to collect sand.
Emergency Generator Diesel Fuel Unloading Area	Storage, use, and unloading of diesel fuel to emergency generators	Diesel Fuel	Storage tanks are double walled, to provide secondary containment and located within metal housing. Daily visual inspections during rounds to ensure no leaks or spills. Spill kit stationed at each generator during filling.
Grounds Equipment Storage Building	Storage of small engine machinery	Gasoline, oil	Quarterly inspections to ensure proper housekeeping.
Waste Veranda (RCRA, Universal, and other wastes)	Storage of hazardous and non-hazardous waste, loading/unloading of waste	See List of Potential Pollutants	Sump valve is closed at all times. See Section 4.1.1 for more detail. Spill response material located on dock.
Overhead fluoride and acid waste lines	Transport of fluoride and acid waste above driveway to the wastewater building	Fluoride and acid waste	Protective structure in place to protect lines Contact Emergency Response Team for incidents.
Snow Removal Equipment Storage	Storage of equipment owned and operated by snow removal contractor	Gasoline, oil	Quarterly inspections of equipment storage area.
Cooling Towers	Preventative maintenance requirement to remove scale and sludge.	Mud, lime scale	Use minimal amount of water in cleaning process. Clean up mud and lime scale and dispose of the materials in the solid waste container.
Wastewater Treatment Building Scrubber	Preventative requirement to wash scrubber	Lime	Use minimal amount of water in cleaning process. Sweep up lime and dispose of the material in the solid waste container.
Driveways	Draining the fire sprinkler system for modifications	Scale from pipes	Drain the fire suppression system the least amount possible.
Driveway	Idaho Power Oil Filled Transformer Maintenance	Oil	Prevent spills during maintenance. Contact Emergency Response Team for incidents.
Landscape/lawn areas	Products applied to landscaping.	Fertilizer, pesticide, herbicide	Follow manufacturer guidelines for application. Clean up spills. Prevent over-watering to limit runoff.

### 3.2 List of Potential Pollutants

Accuglass  
Acetic Acid, EL-UM  
Acetone Total  
AL Etch (Nitric, Acetic, Phosphoric Acids)  
Ammonia Total  
Ammonium Fluoride  
Ammonium Hydroxide Total  
Antimony III Oxide  
Argon Total (gas)  
Arsine (gas)  
Boiler Water Scale Control  
Boron Trichloride (gas)  
Boron Trifluoride (gas)  
Bromine - StaBrEx  
Buffered Oxide Etch Total  
Calcium Carbonate  
Carbon Dioxide (gas)  
Chlorine Total (gas)  
Closed System Corrosion Inhibitor  
Developer Total  
Dichlorosilane (gas)  
Ethyl Lactate  
Ethylene Glycol  
FC77 (perfluorooctane)  
Filter Powder  
Flocculant, Nalclear  
Halocarbon 116 (gas)  
Halocarbon 14 (gas)  
Halocarbon 23 (gas)  
Helium (gas)  
Hexamethyldisiazane (HMDS)  
Hydrochloric Acid Total  
Hydrofluoric acid total  
Hydrogen  
Hydrogen Bromide (gas)  
Hydrogen Chloride (gas)  
Hydrogen Peroxide Total  
Hydroxylamine  
Hypersperse  
Isopropyl Alcohol Total  
Krytox Vacuum pump fluid  
Lime  
Lithium hypochlorite  
LOL 2000 (cyclopentanone)  
Nitric Acid Total  
Nitrogen Total (gas)  
Nitrogen Trifluoride (gas)  
Nitrous Oxide (gas)  
NMP (N-methyl-2-pyrrolidone)  
Octafluorocyclobutane  
Oxygen (gas)  
Phosphine (gas)  
Phosphoric Acid Total  
Phosphorous Oxychloride (gas)  
Photoresist Total  
Polyamide  
Sodium Metabisulfite  
Resist Edge Remover Total  
Silane (gas)  
Slurry Total  
Sodium Hydroxide  
Sulfite Oxygen Scavenger  
Sulfur Hexafluoride Total (gas)  
Sulfuric Acid Total  
Tetraethylorthosilicate (TEOS) Total  
TDMAT  
Triethylborate (TEB)  
Triethylphosphate (TEPO)  
Tungsten Hexafluoride, ULSI  
VM-652 Adhesion Promoter  
Vacuum Pump Scale Control  
Xenon (gas)  
Tungsten Silicon alloy target  
Titanium Tungsten alloy target  
Aluminum Silicon Copper alloy target  
Titanium target  
Aluminum target  
Platinum Nickel alloy target

### 3.3 Salt Storage

There are no storage piles at this facility.

### **3.4 Sampling Data**

Because there has only been outfall from the stormwater detention pond twice in the past 30 years, there is no stormwater discharge sampling data to report. This section will be updated in the event that stormwater discharge sampling is conducted.

## **4.0 STORMWATER POLLUTION CONTROLS**

This section describes the stormwater pollution controls (SWPC) which will reduce the potential to discharge significant amounts of pollutants from the Pocatello site. Many of the management practices included in this Plan are routinely employed by ON Semiconductor; others are based on SWPCs that have been employed to reduce pollutant loads elsewhere. The EPA 2015 MSGP and 40 CFR 125, Subpart K, Criteria and Standards for Best Management Practices Authorized under Section 304(e) of the Act were utilized to develop SWPCs for the Pocatello facility.

### **4.1 Stormwater Management**

Effective stormwater management includes operational BMPs, source control BMPs, and other additional available and reasonable BMPs. The following management practices outlined in the General Permit were included in this Plan:

- Containment is included in Section 4.1.1 as an operational BMP under the materials storage practices and waste chemical disposal.
- Waste Chemical Disposal is included in Section 4.1.1 as an operational BMP.
- Covered Storage or Manufacturing Areas is included in Section 4.1.1 as an operational BMP under the materials storage practices and waste chemical disposal. □
- Stormwater Diversion is discussed in Section 4.1.2 as a source control BMP.
- Debris and Sediment Control is addressed in Section 4.3.1 as part of the stormwater drainage system maintenance and in Section 4.3.5 as part of erosion and sediment controls.

#### **4.1.1 Operational BMPs**

Operational BMPs are practices designed to prevent or reduce stormwater pollution. The following operational BMPs have been implemented or are planned for the Pocatello facility:

#### **Material Inventory Controls**

Material inventory practices can reduce the waste that results from overstocking and disposing of outdated materials. Careful tracking of all materials may also result in more efficient materials use. The following chemical tracking procedures are implemented at the Pocatello facility:

- The Chemical Purchasing Agent and Chemical Logistics Coordinator perform regular inventories of all chemicals onsite.
- Safety Data Sheets (SDS) are maintained for all materials used at the facility. An SDS is obtained and approved by EHS for all new chemicals prior to the chemical being delivered to the facility. Containers are clearly labeled with the name and type of the contained materials. When appropriate or otherwise required, containers are labeled with the hazards of the contained materials, expiration date, suggestions for handling and first aid information.

### **Material Storage Practices**

ON Semiconductor requires proper material storage to prevent the release of materials that may cause stormwater pollution. Proper storage techniques may include:

- Maintaining adequate aisle space to facilitate material transfer and provide easy access for inspections
- Locating containers, drums and bags away from direct traffic routes and in secondary containment to prevent and manage accidental spills
- Storing containers according to the manufacturer's instructions to avoid damage from improper weight distribution

### **Waste Chemical Disposal**

Wastes generated at ON Semiconductor are recycled or disposed of in an appropriate manner and in a way which prevents them from entering stormwater. The following procedures have been implemented for waste management:

- Containers are kept inside buildings or in covered storage areas.
- Items with free liquids are not placed in dumpsters.
- All containers are stored in designated areas, which are covered, paved, free of cracks and gaps, and impervious.
- Reactive, ignitable, and flammable liquid storage methods comply with International Fire Code requirements.
- Drums are stored in controlled-access areas.
- In some areas, portable secondary containment systems are used for temporary storage.
- Employees loading, unloading liquid chemicals, or hazardous waste and support personnel have received training in emergency spill cleanup procedures.

#### **4.1.2 Source Control BMPs**

Source Control BMPs are defined as physical, structural, or mechanical devices or facilities that are intended to prevent pollutants from entering stormwater. ON Semiconductor employs source control BMPs for container storage of liquids and hazardous and non-hazardous waste. These BMPs are discussed in the following

paragraphs.

### **Loading and Unloading of Materials**

The following BMPs have been implemented to address loading and unloading of liquids:

- Hazardous materials are only received at the East Gate Chemical Loading Dock at Chemical Storage Building A. Contained liquids are unloaded or loaded in the loading dock areas so that any spills are contained in the sumps and can be pumped out and disposed of properly.
- From the Chemical Storage Building A, chemicals are moved into the plant in small quantities overseen by the Chemical Logistics Coordinator who is trained in chemical spill response.
- Spill cleanup materials are kept in those areas where liquid spills could occur.
- The areas where materials are transferred from trucks in bulk are sealed for cracks, made of impervious material, and are designed to prevent the runoff of any spill to prevent inflow to stormwater system.
- Bulk lime is unloaded at the Wastewater Treatment Building F. Unloading is performed on impervious surfaces. Good housekeeping practices are used to prevent entrance into stormwater system.

### **Container Storage of Liquids and Hazardous Wastes**

The following BMPs have been implemented for container storage of liquids or hazardous waste:

- Containers are kept inside buildings or in covered storage areas.
- Items with free liquids are not placed in dumpsters.
- All containers are stored in designated areas, which are covered, paved, free of cracks and gaps, and impervious.
- Reactive, ignitable, and flammable liquid storage methods comply with International Fire Code requirements.
- Drums are stored in controlled-access areas.
- In some areas, portable secondary containment systems are used for temporary storage.
- Employees loading, unloading liquid chemicals, or hazardous waste and support personnel have received training in emergency spill cleanup procedures.

#### **4.1.3 Recommended BMPs**

Additional BMPs are recommended for selected areas at ON Semiconductor including areas where there is the potential for significant materials to come into contact with stormwater. These BMPs are summarized in the table below.

Site Description	Recommended BMPs
Waste Storage Areas	<p><b>Employee Training</b></p> <ul style="list-style-type: none"> <li>· Train employees in the proper use of the hazardous waste accumulation areas.</li> <li>· Define good housekeeping standards and conduct chemical safety training.</li> <li>· Train employees in the importance of keeping the ground surface and secondary containment areas clean.</li> </ul> <p><b>Visual Inspection</b></p> <ul style="list-style-type: none"> <li>· Regularly inspect chemical storage areas for spills or leaks, open drums, etc.</li> <li>· Regularly inspect spill pans for spills, leaks or cracks.</li> <li>· Regularly inspect the liquid level of waste containers to prevent overfilling.</li> <li>· Regularly inspect the secondary containment of any waste stored outdoors.</li> </ul> <p><b>Good Housekeeping</b></p> <ul style="list-style-type: none"> <li>· Promptly remove any spills or leaks.</li> <li>· Prior to and following rains, promptly empty drip/spill pans, and secondary containment, if necessary.</li> <li>· 5S+ Program is in place to provide additional attention toward good housekeeping.</li> </ul> <p><b>Substance Containment</b></p> <ul style="list-style-type: none"> <li>· Provide drip pans or secondary containment for all equipment or containers subject to potential spills or leaks.</li> <li>· Provide an overfill protection system for tanks to minimize the risk of spillage during loading.</li> <li>· Surround permanently installed tanks with dikes, which are of sufficient height to provide a volume that is the greater of either 10 percent of the total enclosed tank volume or 110 percent of the volume contained in the largest tank.</li> <li>· Provide dikes and surfaces within the dikes with sufficient impermeability to prevent loss of the stored material in the event of spillage.</li> <li>· Provide outlets from tank containment areas with positive controls to prevent uncontrolled discharge of spilled product.</li> <li>· Incorporate a dead end sump in containment areas for the collection of small spills. This sump should be cleaned regularly to minimize the potential for contamination of stormwater or groundwater.</li> <li>· Release accumulated stormwater frequently during the wet season.</li> <li>· Guard tanks against vehicles with bollards or traffic barriers.</li> <li>·</li> </ul>
Chemical Storage Areas	<p><b>Employee Training</b></p> <ul style="list-style-type: none"> <li>· Train employees on proper chemical handling and inspections.</li> <li>· Train employees on the proper labeling of drums.</li> <li>· Require additional Computer Based Training for employees regularly handling potential pollutants.</li> </ul> <p><b>Visual Inspection</b></p> <ul style="list-style-type: none"> <li>· Inspect chemical containers for leaks, evidence of corrosion and proper labeling.</li> </ul> <p><b>Mitigation Control</b></p> <ul style="list-style-type: none"> <li>· Use brooms or shovels for cleanup of dry materials.</li> <li>· Sweep area after initial bulk cleanup.</li> <li>· Provide spill kits for emergency cleanup.</li> </ul>
Materials Transfer Areas	<p><b>Employee Training</b></p> <ul style="list-style-type: none"> <li>· Train employees on the proper methods of product dispensing.</li> </ul>

Site Description	Recommended BMPs
	Visual Inspection <ul style="list-style-type: none"> <li>· Inspect fueling controls for proper function.</li> </ul> Good Housekeeping <ul style="list-style-type: none"> <li>· Promptly remove any spills or leaks.</li> </ul>

## 4.2 Spill Prevention Response Procedures

The areas where potential spills of significant materials can contact and contaminate stormwater discharge are shown on Figure 2 of this SWPPP. ON Semiconductor transfers, stores, and uses hazardous materials throughout the fabrication process. Subsequently, small leaks and spills may occur, which could contribute to stormwater pollution. ON Semiconductor has developed Accidental Spill Prevention Program (ASPP) to minimize the potential for stormwater pollution from small leaks and spills. See Appendix 2 for the ASPP.

## 4.3 Preventive Maintenance

A Preventive Maintenance Program is required to ensure the effective operation of material management facilities, control facilities, and treatment facilities to comply with the requirements of the permit. The program involves the inspection and maintenance of equipment and systems to uncover conditions that could cause breakdowns and correction of those conditions by adjustment, repair, or replacement of worn parts before the equipment or systems fail. One goal of the program is to modify conditions that could result in discharges of pollutants to storm drains or surface waters. The Preventive Maintenance Program therefore includes inspection and maintenance of the stormwater drainage system. The Preventive Maintenance Program involves:

### 4.3.1 Stormwater Drainage System Maintenance

Maintenance of the stormwater drainage system includes:

- Identifying equipment and systems which could potentially fail and release significant materials
- Adjusting, repairing, and replacing parts and equipment when necessary
- Maintaining records of deficiencies and corrective actions
- Cleaning and repairing stormwater catch basins

### 4.3.2 Inspections

Since inspection records can enable early detection of potential problems, ON Semiconductor documents all inspections as a good preventive maintenance technique. Records are kept which document spills, leaks and other discharges, including discharges of hazardous substances in reportable quantities. Records summarizing the

scope of inspections, any major observations relating to the implementation of the SWPPP, and any required modifications are also retained. All records are retained in accordance with corporate policy.

Stormwater catch basins are inspected and are cleaned as needed. If the structural integrity of any storm drainage facility deteriorates, the facility is repaired in a timely manner.

### **4.3.3 Good Housekeeping**

Good housekeeping involves maintaining a clean and orderly work environment to reduce the possibility of accidental spills caused by mishandling of equipment. Examples of good housekeeping practices employed by ON Semiconductor include:

- Neat and orderly storage of chemicals
- Prompt cleanup and removal of spillage
- Regular pickup and disposal of garbage and rubbish
- Provisions for proper storage of containers
- Prevention of liquid or solid chemical accumulation on the ground or the floor
- Implementation of 5S+ program to focus attention on good housekeeping

### **4.3.4 Facility Maintenance**

Regular maintenance is needed to ensure that the facility is functioning as desired. The Facility Maintenance Department at ON Semiconductor executes the following operating and maintenance BMPs as part of the good housekeeping program at the facility:

- Work surfaces, floors, and ground surfaces are kept clean and dry
- Garbage and other solid waste is picked up regularly for disposal
- Equipment is routinely inspected for leaks or conditions which could lead to pollutant discharges or stormwater coming in contact with raw materials or waste
- Equipment, when not working properly, is promptly taken out of service for repair

### **4.3.5 Erosion and Sediment Controls**

ON Semiconductor minimizes erosion by stabilizing exposed soils in order to minimize pollutant discharges. Parking lots and driveways are swept annually to remove sediment that could potentially enter the stormwater system. All local regulations pertaining to erosion and sediment controls are observed, including City requirements for projects that disturb one acre or more.

## **4.4 Employee Education**

ON Semiconductor maintains a training program for preventing stormwater pollution as

part of the Environmental, Health, and Safety portion of the New Hire Orientation as well as the annual EHS Training that all employees are required to complete. Employee training is essential to the effective implementation of the SWPPP. The purpose of the employee-training program is to inform personnel, at all levels, of the responsibilities, components, and goals of the SWPPP.

Training topics include spill prevention and response, good housekeeping and material management practices. Tools used during these training sessions may include employee handbooks, slide presentations, handouts, drills, or role-playing to emphasize the requirements for:

- Identifying potential spill areas and drainage routes
- Reporting spills to appropriate individuals
- Specifying material handling procedures and storage requirements
- Identifying spill response procedures

On-site contractors and temporary personnel are also informed of facility operational and design features in order to help prevent accidental discharges or spills from occurring. This training is administered through the annual EHS computer based training.

Finally, ON Semiconductor Facility Operations Technicians and Maintenance personnel will be trained on how to maintain a clean and orderly work environment. The training will incorporate the following topics:

- The importance of good housekeeping measures completed on a regular basis
- The prompt cleanup of spilled materials to prevent stormwater contamination
- The locations where brooms, vacuums, absorbents, and other good housekeeping and spill response equipment are stored
- The use and management of drums and containers and checking for leaks and spills
- Maintaining a regular schedule for housekeeping
- Proper loading/unloading of fuel for emergency diesel generators

## **5.0 Inspections, Recordkeeping, and Internal Reporting Procedures**

Routine facility inspections will be conducted at least quarterly. Per the 2015 MSGP §3.1, at least once each calendar year, the routine inspection will be conducted during a period when stormwater discharge is occurring. Because this facility rarely has stormwater discharge, this may not be possible. The Stormwater Inspection Form that is included in Appendix 3 of this Plan will be completed for facility inspections.

Given that Pocatello is located in a semi-arid region, the samples for the quarterly visual assessments will be distributed during seasons when precipitation runoff occurs as prescribed in §3.2.3 2015 MSGP. Visual inspection of snowmelt runoff will be

performed during a period of measurable discharge. As prescribed in the 2015 MSGP, quarterly visual assessments will be taken the outfall. The only outfall in the ON Semiconductor Pocatello stormwater system is the overflow drain for the retention pond. Water has reportedly exited this drain less than two times in the last 30 years. In the event that this outfall is used in the future, corporate requirements in document number 12MON00367D (Surface Water) and the following 2015 MSGP guidelines will be observed:

At least once a quarter, a visual inspection of the stormwater runoff will be collected from the outfall location indicated in Figure 2 and examined using the Quarterly Visual Inspection Form included in Appendix 4 of this Plan. This visual inspection will be conducted during the first 30 minutes of a rainstorm, if possible, and at least 3 days from previous discharge. It will include observations for the following water quality characteristics:

- Color
- Odor
- Clarity (diminished)
- Floating solids
- Settled solids
- Suspended solids
- Foam
- Oil Sheen
- Other obvious indicators of stormwater pollution

Whenever the visual assessment shows evidence of stormwater pollution, corrective action procedures will be initiated as outlined in Section 4 of the 2015 MSGP.

**Additional Requirements:** in addition to corporate requirements and 2015 MSGP requirements, the EPA Region 10 Office added the following additional requirements:

Part 2.2.2.1 of the MSGP, Existing Discharge to an Impaired Water with an EPA Approved or Established TMDL, states, “If you discharge to an impaired water with an EPA-approved or established TMDL, EPA will inform you whether any additional measures are necessary for your discharge to be consistent with the assumptions and requirements of the applicable TMDL and its waste load allocation, or if coverage under an individual permit is necessary per Part 1.2.3.” See also Part 6.2.5 of the MSGP (allowing EPA to notify a facility of additional monitoring requirements).

In a 2016 communication from the EPA Region 10 Office, ON Semiconductor Pocatello was notified of additional requirements because the facility has a potential to discharge to the Portneuf River, which is listed as impaired for flow alteration, fecal coliform as measured by *Escherichia coli* (*E. coli*), oil and grease, suspended sediment, and total phosphorus. Because the State of Idaho Department of Environmental Quality (IDEQ) has established Total Maximum Daily Loads (TMDLs) for these, should the facility have a stormwater discharge, it is required to conduct stormwater monitoring for *E. coli*, oil and grease, total phosphorus, and total suspended solids. In the event that ON

Semiconductor Pocatello has outfall, this discharge monitoring will be completed. During quarters where there is no outfall, “no discharge” reports will be submitted through the EPA NetDMR system. Copies of these “no discharge” reports will be sent to the IDEQ.

ON Semiconductor to performs preventive Maintenance Inspections (PMIs):

- Increase the life of equipment and facilities through routine periodic maintenance
- Improve safety by ascertaining the reliability of facility equipment
- Reduce equipment downtime and ensure the readiness of all parts of the facility

Records and reports will be maintained in accordance with corporate policy:

- All significant events, such as spills or releases, which result in stormwater pollution
- In-house inspection reports, follow-up responses to any deficiencies noted during inspections
- Documentation describing any significant changes in on-site activities
- Records of 5S+ program

To meet a corporate requirement for review, identification, and evaluation of potentially contaminated surface water sources from adjacent properties, a line item for inspection of Adjoining SW Contributing Properties was added to the Stormwater Inspection Form in Appendix 3 of this Plan. In addition, to meet a corporate requirement for inspection of secondary containment of any hazardous liquids stored outdoors, a line item for inspection of secondary containment at the Chemical Warehouse has been added to the Stormwater Inspection Form in Appendix 3 of this Plan.

## **5.1 Records Requirements**

ON Semiconductor will maintain records of all monitoring information according to corporate policy. Records of monitoring information shall include:

- Sample location
- Sample collection date and time, and visual assessment date and time for each sample
- Personnel collecting the sample and performing visual assessment, and their signatures
- Nature of the discharge (i.e., runoff or snowmelt)
- Results of observations of the stormwater discharge
- Probable sources of any observed stormwater contamination
- If applicable, why it was not possible to take samples within the first 30 minutes
- A statement, signed and certified in accordance with Appendix B, Subsection 11

of the 2015 MSGP

- Any corrective action required because of a quarterly visual assessment will be performed consistent with Part 4 of the 2015 MSGP.

The official signed copy of this Plan will be stored electronically on a public website per the requirements of the 2015 MSGP; however, a working copy will be maintained on the internal Pocatello EHS webpage. The working copy will be updated as needed for minor additions that do not require a complete SWPPP modification for public posting. A revision history table is maintained at the end of this Plan to document changes.

## **6.0 DOCUMENTATION TO SUPPORT ELIGIBILITY CONSIDERATIONS UNDER OTHER FEDERAL LAWS**

### **6.1 Documentation Regarding Endangered and Threatened Species and Critical Habitat Protection**

See Appendix 5 for documentation supporting determination that there are no endangered or threatened species and no critical habitats within the ON Semiconductor Pocatello property.

### **6.2 Documentation Regarding Historic Properties Preservation**

See Appendix 6. As an existing facility that gained coverage under the 2008 MSGP, ON Semiconductor Pocatello has certified that it has not affected historic properties, and because this facility is not constructing or installing any new stormwater control measures, it has met eligibility Criterion A of the 2015 MSGP.

## **7.0 PLAN CERTIFICATION**

I certify under penalty of law that this document and all attachments were prepared under my direction or supervision in accordance with a system designed to assure that qualified personnel properly gathered and evaluated the information submitted. Based on my inquiry of the person or persons who manage the system, or those persons directly responsible for gathering the information, the information submitted is, to the best of my knowledge and belief, true, accurate, and complete. I am aware that there are significant penalties for submitting false information, including the possibility of fine and imprisonment for knowing violations.

Name: Teri Bowman Title: Environmental Engineer

Signature: \_\_\_\_\_ Date: September 15, 2018

## REVISION HISTORY

Revision	Change Originator	Description and reason of Change	Approved By	Effective Date
1	Neil Jenkins	Added water drained from fire sprinkler modifications and Oil filled transformer maintenance to Significant Materials Table. Added Idaho State University Technology and Business Park and Idaho Department of Health and Welfare to the potential run-on sources.	Staci O'Connell	Feb 11, 2011
2	Neil Jenkins	Revised catch basin cleaning to be as needed.	Staci O'Connell	Jun 24, 2011
3	Marcie Lewis	Revised §5.0 Schedule to include specific intervals and periods for inspections and assessments per the 2008 MSGP. Also in the same section, removed the reference to the EHS SharePoint calendar.	Staci O'Connell	Aug 6, 2014
4	Marcie Lewis	Changed "Change Analyst" in Revision History table to "Approved By."	Staci O'Connell	Oct 28, 2014
5	Marcie Lewis	Updated to reflect requirements of 2015 MSGP.	Staci O'Connell	Oct 20, 2015
6	Marcie Lewis	Added the requirement for secondary containment inspection for any hazardous liquids stored outdoors.	Staci O'Connell	Nov 5, 2015
7	Marcie Evans	Clarified corporate requirements for sampling outfall by referencing 12MON00367D – Surface Water.	Staci O'Connell	May 18, 2016
8	Marcie Evans	Added Portneuf TMDL monitoring requirements per letter received from EPA Region 10 Office.	Staci O'Connell	July 11, 2016
9	Marcie Evans	Annual review. No changes.	Staci O'Connell	Sep 30, 2016
10	Teri Bowman	Annual review. No changes	Staci OConnell	Sept. 27, 2017
11	Teri Bowman	Updated to be consistent with what was in Pocatello's Emergency Response plan, for ASPP, and Spill Response and cleanup		Sept. 15, 2018
12	Teri Bowman	Update spill kit location and inventory tables, minor changes throughout document		July 18, 2019

## Appendix 1 – Figures and Maps



Figure 1: General Location Map – from Esri (Environmental Systems Research Institute) ArcGIS software ([www.arcgis.com](http://www.arcgis.com))

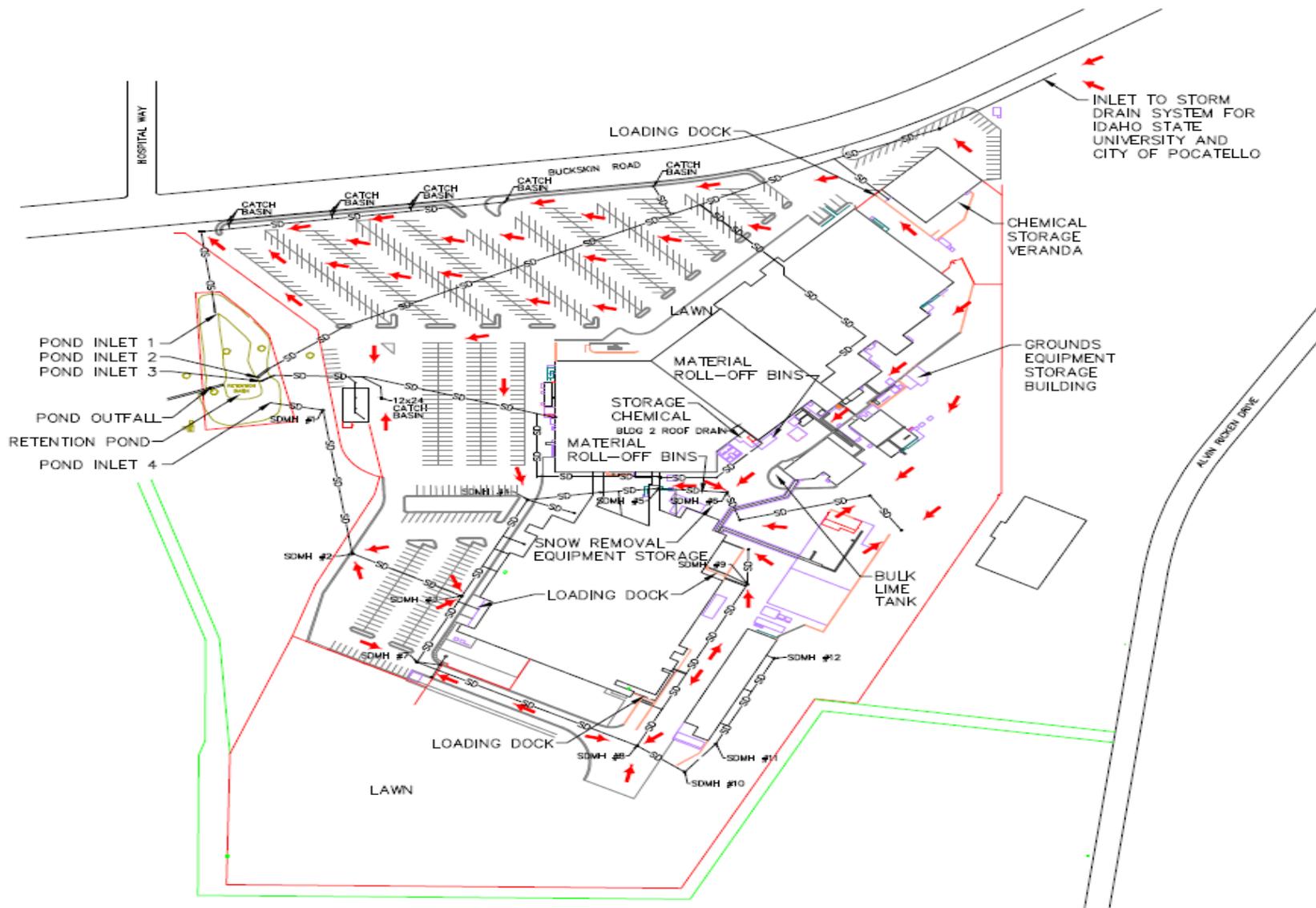


Figure 2: Site Map (arrows indicate direction of stormwater flow)

## **Appendix 2 – ASPP and Chemical Spill Response Procedure**

These procedures are appendices to the ON Semiconductor Pocatello Emergency Response Plan. Refer to the current Agile document for the most current procedures. These excerpts have been edited to remove individual names and replace them with job titles.

### **ON Semiconductor Pocatello Accidental Spill Prevention Program (ASPP)**

The purpose of this program is to minimize the potential for, and risk of, an uncontrolled hazardous material release. It applies to all ON Semiconductor property and buildings located at 2300 Buckskin Road, Pocatello, Idaho 83201. It DOES NOT include the real property and materials associated with the Praxair operation located on the south section of the ON Semiconductor Pocatello property.

### **Consequences of Accidental Spills and Discharges**

Willful or accidental actions causing a spill or discharge of a hazardous material can result in regulatory violations and fines. If a spill or discharge is improperly handled, it may also result in having the facility's environmental permits revoked.

### **Corrective Actions**

Spill containment, cleanup, and release notification will follow ON Semiconductor procedures described within the Chemical Spill Cleanup Procedure and the Emergency Response Plan.

### **Reporting and Notification**

ON Semiconductor Pocatello has an Industrial Wastewater Discharge Permit that defines treatment methods, facility management requirements, and discharge parameters. As an element of that permit, the facility conducts continuous and periodic monitoring, and reports those results to the City of Pocatello. If it is discovered that a discharge parameter has been exceeded, the Environmental Engineer will provide verbal notification to the Pretreatment Coordinator within 24 hours of discovery. This notification will be followed, within 5 days, by a written notice describing the cause of the discharge, actions taken, and corrective actions to prevent future occurrences. The same 24-hour verbal, and 5 day written follow-up is required when a slugload occurs ("slugload" is defined below under *Permit Limitations*).

**Immediate verbal notification**, followed by written notification within 5 days, is required for the following events:

1. Spill of hazardous material that reaches the storm sewer or water of the State, or a
2. Treatment upset that places the discharge in temporary noncompliance with wastewater discharge limitations contained in the permit, or other limitations specified in the City's ordinance.

Annually, Pocatello ON Semiconductor provides the City with a chemical inventory showing a list of the chemicals used, and quantities purchased for the year. This report is provided on, or before April 1 of each year.

If the facility plans to introduce new wastewater pollutants, change manufacturing operations, or substantially change the volume or characteristics of the wastewater being discharged, a 90-day notice to the City of Pocatello is required. This notice can be provided in person, or by telephone. Formal, written notification is required at least 10 days prior to the change. City approval is required prior to the change

**Permit limitations:**

1. 19,500,000 gallons per month of waste water to sanitary sewer
2. Monthly average flow: 650,000 gallons per day
3. Maximum Daily flow: 840,000
4. Maintain a pH of not less than 6.0 or greater than 10.

Parameters	Units	Daily Minimum	Daily Maximum	Daily Average	Sample Type
Industrial Flow	gal/day	---	840,000	650,000	Continuous
pH	units	6.0	10.0		Continuous
Temperature	Degrees F	---	104		Continuous
BOD <sup>4</sup>	lb/day	---	---		---
TSS <sup>4</sup> (Total Suspended Solids)	lb/day	---	---		---
Oil and Grease (Petroleum)	mg/L	---	100		24-hr Composite
FOG <sup>1&amp;4</sup> (Animal and Vegetable)	mg/L	---	350		24-hr Composite
Fluoride <sup>5</sup>	mg/L	---	32.0		24-hr Composite
TKN (Total Kjeldahl Nitrogen) <sup>4</sup>	mg/L	---	---		24-hr Composite
Total Phosphorous <sup>4</sup>	mg/L	---	---		24-hr Composite
Arsenic (T) <sup>2</sup>	mg/L	---	0.05		24-hr Composite
Cadmium (T) <sup>2</sup>	mg/L	---	0.28		24-hr Composite
Chromium (T) <sup>2</sup>	mg/L	---	3.2		24-hr Composite
Copper (T) <sup>2</sup>	mg/L	---	0.515		24-hr Composite
Lead (T) <sup>2</sup>	mg/L	---	0.195		24-hr Composite
Mercury (T) <sup>2</sup>	mg/L	---	0.00067		24-hr Composite
Molybdenum (T) <sup>2</sup>	mg/L	---	0.12		24-hr Composite
Nickel (T) <sup>2</sup>	mg/L	---	0.42		24-hr Composite
Selenium (T) <sup>2</sup>	mg/L	---	0.107		24-hr Composite
Silver (T) <sup>2</sup>	mg/L	---	0.62		24-hr Composite
Zinc (T) <sup>2</sup>	mg/L	---	1.87		24-hr Composite
TTO <sup>3, 5</sup>	mg/L	---	1.37		24-hr Composite

Notes:

1. FOG = Fats, Oil, and Grease
2. (T) = Total Metals
3. TTO = Total Toxic Organic. Equals the summation of all values greater than 0.01 mg/L for each of the toxic organics specified in 40 CFR 122, Appendix D; Table II. ON is only required to test the "Volatile" Pollutants (Method EPA 624)

4. Strength and volume charges apply for these parameters. The City will provide the analysis for the strength charge pollutants.
5. Categorical Effluent limitations specific in CFR 40 469, Subpart A

Notes:

1. FOG = Fats, Oil, and Grease
2. (T) = Total Metals
3. TTO = Total Toxic Organic. Equals the summation of all values greater than 0.01 mg/L for each of the toxic organics specified in 40 CFR 122, Appendix D, Table II.
4. Strength and volume charges apply for these parameters. Ammonia will be used in place of TKN. The City will provide the analysis for the strength charge pollutants.
5. BTEX will be measured as the sum of benzene, ethyl benzene, toluene, and xylene.  
**Slugload:** Any discharge at a flow rate or concentration, which could cause a violation of the prohibited discharge standards including, but not limited to, an accidental spill or a non-customary batch discharge.

## SPILL PREVENTION

### Chemical Acquisition

As required by our Site policy, if an employee wishes to bring a new chemical in-house, they must first fill out a New Chemical Evaluation Request Form. All new chemical requests are reviewed by the Environmental and Safety Engineer to ensure that proper training, handling, storage and disposal procedures are in place prior to chemical introduction. A member of the EHS department is also on the Oracle chemical purchase approval loop to ensure all requested chemicals have gone through the New Chemical Evaluation process.

### Chemical Management

Chemicals are managed at the facility in a manner to prevent potential spills. Chemical storage procedures include the following:

- Chemicals are stored only in secured areas
- Chemicals are not stored in areas where there is high pedestrian or vehicle traffic
- Chemicals are stored in secondary containment, or in areas where, if a spill occurs, it will be contained within an isolated area or via the permitted wastewater treatment system
- All hazardous materials are stored in compatible containers
- Employees responsible for handling and storing chemicals have received training on proper handling and storage
- Security Services personnel patrol chemical storage areas on each shift. Part of the inspection protocol includes chemical storage
- 5S audits/inspections are performed on a regular basis and part of the protocol includes chemical storage
- The facility has surveillance cameras and limited access controls for the chemical warehouse area

## **Accidental Discharge Prevention**

Pocatello ON Semiconductor manage chemical to prevent accidental discharges. Chemical management procedures include the following:

- There are hazardous gas monitors in areas where Hazardous Production Materials (HPMs) are used or stored. If a release occurs, the air monitors are likely to detect it and initiate an emergency response resulting in release mitigation before a discharge occurs.
- Security Services personnel patrol chemical storage areas on each shift, if a spill is discovered Security initiates an immediate response.
- Response procedures are outlined in the response guidebook and flow chart.
- EHS reviews process changes and new equipment installations to ensure proper secondary containment and waste collection is included.
- Chemicals are not stored near floor drains.
- Chemicals are not stored outside in areas where a spill would result in an environmental discharge.
- Chemicals do not get poured down sanitary drains.
- The facility has a formal Waste Management Program that defines appropriate disposal procedures for chemicals.
- Floor holes, and drains routed to sanitary sewer, are sealed.
- The wastewater treatment system has automated, on-line monitoring systems to track hazardous material concentrations, and will alarm if discharge limits are exceeded.
- Install manufacturing tools in a manner to ensure waste streams are routed to the appropriate collection systems.
- Manufacturing tools that use hazardous liquids are installed with secondary containment systems to contain spills.
- There are spill response kits located throughout the facility, in the event of a spill, it can be contained and remediated before it becomes an environmental discharge.
- The facility has an Industrial Wastewater Discharge Permit that defines treatment methods, facility management requirements, and discharge parameters to prevent accidental discharges.
- All pipe works for chemicals are enclosed in trenches or contained in secondary containment pipes for spill containment.
- Employees and contractors are instructed they are NOT to come onto the property with hazardous materials stored in their vehicles (e.g., gas cans, oilcans, paint cans, fuel-burning gardening equipment, etc.).

## **CHEMICAL SPILL RESPONSE PROCEDURE**

In many cases, chemical spills involve small quantities of materials and, if precautions are taken, present minimal hazards. The responsible party is usually the most appropriate to clean up their spills because they are more likely than others to be familiar with the spilled material's hazardous characteristics, can respond rapidly, are aware of other potential hazards or complicating factors in their work area, and should be familiar with the proper cleanup techniques for a particular spill. However, some spills will require contacting SCC to activate the ERT, and potentially the use of outside assistance, because of the spill's size or hazards. This procedure provides guidance on determining the hazard severity of a spill and the procedures to implement based on the determined hazard severity.

### **Spill Hazard Severity**

Three factors primarily determine if a hazardous materials spill is minor or major. If any of the following apply, the spill is considered major.

1. Size – more than 100 ml/10 grams of an OSHA regulated chemical carcinogen or highly hazardous chemical or 1 liter/100 grams of a volatile or flammable solvent, reactive, or corrosive (acid or base) liquid/solid.
2. Hazards – below the above identified threshold, but, present an immediate danger to health, safety, or the environment, is unknown, or is an immediate fire hazard. All mercury spills are considered major and require the implementation of the major spill response procedures.
3. Location – outside of an area where the material is normally used, and/or there is no trained person available to clean up the spill.

### **ON Semiconductor Pocatello SPILL RESPONSE PROCEDURES**

If an employee or contractor discovers a hazardous material spill, they must follow the systematic procedures listed below:

1. If the spill creates a potentially dangerous environment, leave the area and ensure that all other employees and contractors leave the area.
2. Prevent anyone from entering the area.
3. Contact our Security Control Center by dialing “3333”, the emergency notification number, and provide as much information as possible. Do not hang up until instructed to do so.
4. If it is safe to do so, continue to monitor the affected area to prevent people from entering.
5. If Security Control deems it necessary to initiate an emergency response, remain available to answer any questions the Incident Commander might have.
6. Security Control will use the following form and flowchart, in determining the appropriate response.

## HAZARDOUS MATERIAL SPILL

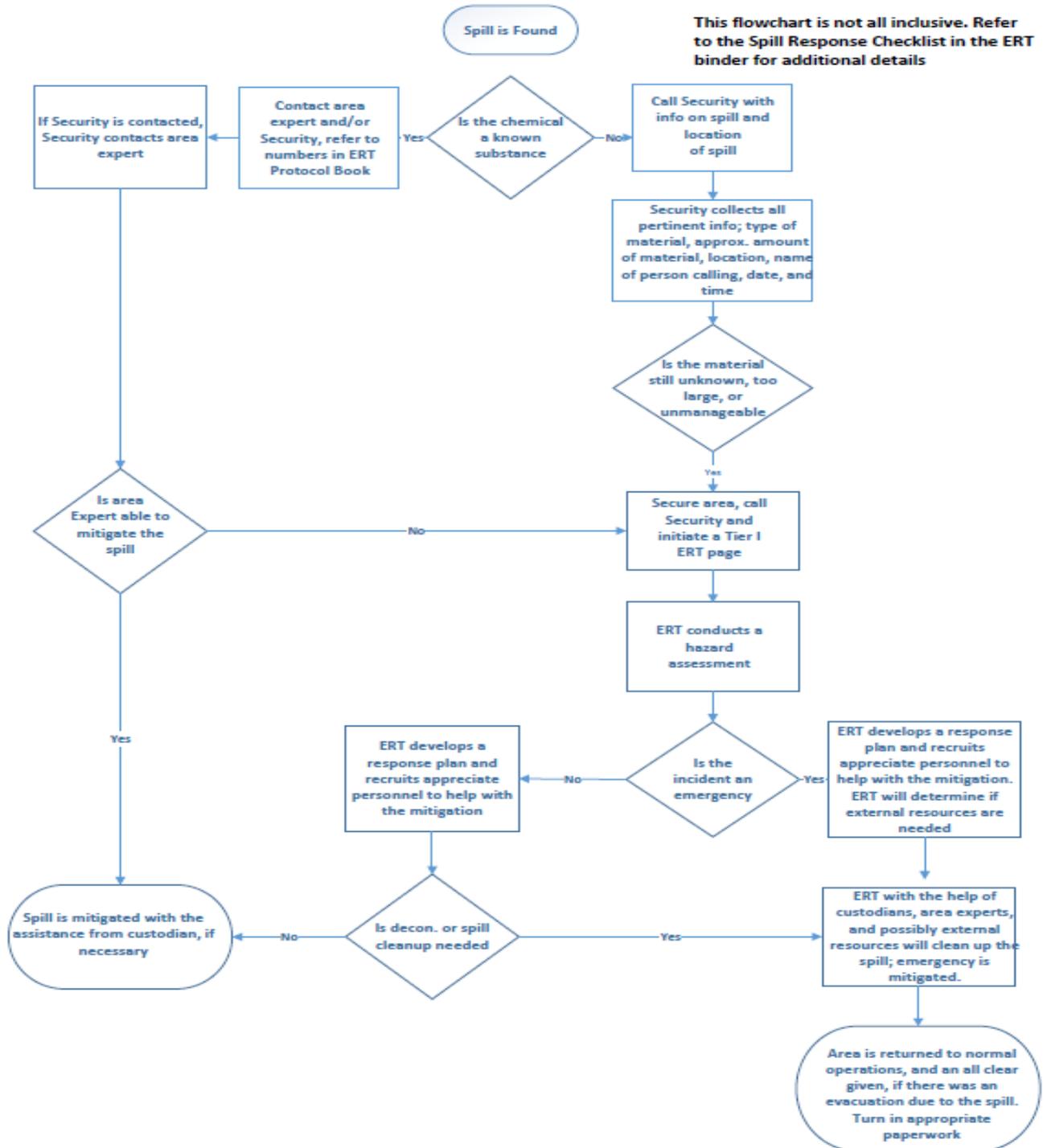
In the event of a hazardous material spill, follow these guidelines:

### STEP 1: DISCOVERY

Call Security at x3333, indicating a hazardous material spill. Security collects the following information:

1. Caller's name
2. Is the caller safe at the location from which they are calling
3. Caller's location
4. Extension/Spectra link/Cell phone number at which the caller can be contacted if he/she is disconnected
5. Location of the spill
6. What is the spilled material
7. Is there more than one material involved
8. Is the spill near a drain (e.g., floor drain or stormwater drain)
9. How large is the spill
10. Is the material still spilling
11. What caused the spill
12. Is a spill Kit nearby
13. Is there a witness to how the spill was initiated, and if so, what is his/her name

**STEP 2: FOLLOW THE SPILL RESPONSE FLOWCHART BELOW**



**IF THE ON-SITE ERT IS REQUIRED, ISSUE A TIER I PAGE (Tier one denotes a page distribution option within the paging application)**

- Issue a Tier I page that provides the following information:
  1. "Response is required"
  2. "A spill of (*fill in the material name*) has occurred in/at (*fill in the location*)"
  3. "Report to (*fill in the location*)"
- If communication systems fail:
  1. Use overhead paging system to call ERT, using the following language:
  2. "This is Security Control. We have an ERT paging system failure, all ERT members please report to (*fill in the location*)"
  3. Using the current SCC emergency phone number list, call the following people:  
 EHS Manager  
 Safety Engineer  
 Environmental Engineer

**IF ERT ASSISTANCE IS NOT REQUIRED, BUT AREA EXPERTS ARE REQUIRED**

- Send a page to the appropriate people:

<b>If you need</b>	<b>Primary contact</b>	<b>Backup contact</b>	<b>Backup contact</b>
Instructions for spill cleanup	EHS Manager	Safety Engineer	Environmental Engineer
Chemical compatibility information	Environmental Engineer	EHS Manager	Safety Engineer
Information on personal protective equipment	Safety Engineer	EHS Manager	EHS Technician
Information on respiratory protection	EHS Technician	Safety Engineer	EHS Manager
Chemical distribution shut off	Plant Operations	On-shift personnel	On-shift personnel
Water shut off	Plant Operations	On-shift personnel	On-shift personnel
Power shut off	Plant Operations	On-shift personnel	On-shift personnel
Information about sending liquids to the Wastewater Treatment Bldg.	Plant Operations AND EHS Manager and Environmental Engineer	On-shift personnel	On-shift personnel
Information about properly containing, labeling, and storing spilled material	EHS Manager	Environmental Engineer	Material Handling Technician
Help with HGMS monitors	Facilities PFG Engineer	Facilities Gas Technician	Facilities Electrical Engineer
Instructions or assistance with portable monitors	Facilities Gas Technician	Facilities Gas Technician	Facilities Manager
Questions regarding workplace injuries and illnesses	Site Nurse	Corporate Nurse	EHS Manager
Additional assistance with safety	Safety Engineer	EHS Manager	EHS Technician
Additional assistance for environmental questions	EHS Manager	Environmental Engineer	Safety Engineer

## **SPILL CLEANUP**

Emergency responders must know how to use techniques that minimize or prevent harm to life, the environment, or property. An improper action, regardless of good intentions, can risk the lives and health of many people and cause permanent environmental damage.

Each spill situation creates a different set of problems for emergency response personnel. Every incident will vary according to the amount and type of hazardous materials spilled, the resources available, as well as numerous other factors, e.g., location, ventilation, other materials and potentially affected equipment.

The first objective is to prevent a hazardous material from escaping a damaged container - to stop the flow of the material from its container. This is known as "containment."

The second objective, "confinement", is to prevent the dispersal of a hazardous material that has already been spilled or otherwise released from its container.

## **STEPS IN SPILL/LEAK RESPONSE**

The response to incidents involving the release or the potential release of a hazardous material involves the following steps.

1. Evaluate the situation – identify the spilled substance, if substance is unknown, treat material like it is high toxic. All spill kits contain pH strips and a chemical safety handbook to help identify chemicals.
2. Don PPE – use appropriate PPE to protect yourself. Chemical resistant suit, gloves, and goggles should always be worn
3. Contain – stop flow at the source. Use absorbant materials to contain the spill and prevent it from causing further contamination; upright container if safe to do so
4. Confine - prevent material release from spreading
5. Clean up the spill - recover spilled material for proper disposal
6. Dispose – properly dispose of all materials used for cleanup, including PPE
7. Report – Notify EHS for reporting requirements

After the Tier 1 page is initiated, the first step for responding is to identify an Incident Commander (IC). According to federal regulations, an Incident Safety Officer (ISO) must also be assigned at hazardous material incidents.

In the event of a "non-emergency" spill cleanup, area experts or hazardous material specialists shall direct the activities of those individuals assigned to perform spill cleanup.

## **SPILL/LEAK CLEANUP TECHNIQUES**

### **Extremely Hazardous Substance Spills**

ON Semiconductor Pocatello uses two materials, classified by the Environmental Protection Agency as extremely hazardous substances (EHS), which have a reportable quantity <sup>1</sup> of < 1 pound. They are mercury and arsenic. The facility has implemented a response policy specific to these three materials. A spill of any amount, for any of these two materials, Security Control must be notified.

#### **Arsenic**

The facility has an OSHA-compliant Arsenic Program, which includes arsenic-trained employees. Arsenic-trained employees shall clean up all spills of arsenic, and will operate as the area experts under the direction of the Incident Commander.

#### **Mercury**

Mercury spills will be cleaned up using the Emergency Response Team (ERT) and a hazardous material specialist. Depending on the location and quantity of the spill, an area expert may also be required. Mercury spill kits are maintained in the Facility's Stores area (c8 b2 id-65619).

Spill or leak cleanup techniques begin with identifying and controlling the spilled material. Control methods can be categorized according to the objective, whether to contain or confine the released material.

#### **Solids**

Solids, such as dust, powders, granules, or solid chunks are probably the easiest to deal with because gravity tends to keep them in one place. Examples of confinement techniques for solids include:

- Over packing ruptured barrels
- Covering the solid material to prevent spreading
- Repacking the material into secondary containers
- Minimize airborne particles during cleanup activities

#### **Liquids (acids & bases)**

- Test all chemical spills with pH paper. Depending on the color of the pH strip will depend on whether the chemical is an acid or base.
- Liquids, unlike solids, spread quicker
- Upright container if safe to do so
- Contain the spill with absorbent material, such as pads, lime, soda ash, or kitty litter to clean up the spill

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<sup>1</sup> Reportable Quantity: The quantity at which, if an environmental release exceeds, appropriate authorities must be notified.

- Covering the liquid to prevent dispersal of vaporous fumes that may disperse from the liquid material
- After materials are cleaned up, mop the spilled area at least three times using fresh water.
- Double-bag, label, and date the bag of debris (contaminated mop head, PPE, absorbent materials, etc.)
- Place double-bagged debris in room 428, send email and/or call the shipping and receiving clerk, who manages hazardous waste, and the Environmental Engineer

Confining liquids requires special considerations. Compatibility of the spilled material with all equipment and supplies (e.g., absorbent pillows and kitty litter) must be determined. If covering the material is a consideration, be aware of any toxic or flammable vapors that may accumulate.

### **Flammables (Photo Resist & Solvents)**

- Remove all ignition sources from the area, if safe to do so
- Contain the spill with absorbent material, such as floor dry, kiln dust, or pads
- Double-bag, label and date the bag of debris (contaminated PPE, absorbent materials, etc.)
- Place double-bagged debris in room 428, send email and/or call the shipping and receiving clerk, who manages hazardous waste, and the Environmental Engineer

### **Gases and Vapors**

Substances in the gas state are undoubtedly the most difficult to control. Unlike solids or liquids, gases tend to engulf an area in all directions at once. Moreover, a particular gas may have the tendency to rise or stay close to the ground (based on vapor density). Gases with a vapor density of less than 1.0 have a tendency to rise in air, while those greater than 1.0 have a tendency to sink.

When dealing with gases or vapors, airflow and ventilation are important considerations. Opening doors and windows can enhance ventilation of the area, yet consideration must be given to where the material will flow, and the safety and environmental impact of releasing the material.

### **Tools and Equipment**

A variety of techniques for emergency spill response involves using tools and materials that are readily available at the Pocatello ON Semiconductor Facility. In order to facilitate quick response to any emergency spill situation, there are spill kits in several vital locations throughout the facility. Spill kit locations and kit contents are provided in the tables below:

### SPILL KIT LOCATIONS

#1. Building D, Fab 9 hallway near elevator, Level 100
#2. Building C, Facilities near Room #424, Level 100
#3. Building H, Room #2130, Level 79
#4. Building H, Room #2109, Level 79
#5. Building H, Near Stair #1, Level 79
#6. Building H, CMP Room #2240, Level 100
#7. Building H, Hallway #2217, Near wipe down area, Level 100
#8. Building D, CDS Area, Level 88
#9. Building A, Level 100
#10. Outside of Building H, Fab 10 South Shipping Dock
#11. MA Lab, near entrance to chemical lab area
#12 Building B Energy Center
#13 Inside cleanroom,, sub-fab level, wall next to implant and Photo area

### #1 SPILL KIT CONTENTS

Skill Kit Supplies	Quantity
Absorbent Mats (Gray)	20
Absorbent Mats (Pink)	20
Acid Aprons	3
Acid Booties	5
Acid Gloves	5
BBP/None Acid	2
Blue Chem Resistant Suits	2
Boots	5
Chemical Safety Handbook	1
Class "B" Chem Suit	2
Drip Bucket	1
Fab Towels	100
Face Shield	2
Flashlight	1
Goggles	2
Mop Heads	1
PH Sticks	1
Pig Socks	2

Red Danger Sign	5
Tape (Clean Room)	1
Tape (Red No Entry)	1
Tape (Yellow Caution)	1
Waste Stream Bags (Red, Black, White)	10
White Tyvek Suits	5
Yellow Caution Sign	5

- Some kits may have yellow absorbent mats, which are mainly used for materials such as: water, petroleum and chemical-based fluids
- These kits and supplies are inventoried and maintained by the Safety Engineer and ERT
- Spill kits # 3 and #5 also contain two harnesses for confined space entry. **Only those individuals who have been trained and qualified in confined space entry may use this equipment**

Below is a list of additional equipment that may be used during spill cleanup.

#### **ADDITIONAL SPILL RESPONSE EQUIPMENT**

<b>EQUIPMENT</b>	<b>LOCATION</b>
Water Separators	900 Hall Near Elevator Annex Central Clean Service Bay
Wet/Dry Vacuums	Custodian Room 371
Floor Squeegee	Custodian Room 371 PF&G Area Near Main Shop
Mop Buckets	Most Custodial Closets
Fans	Level 88 Room 1160 (dungeon) Energy Center
Carpet Extractor	Custodial Room 371
Push Brooms / Shovels	Most Custodial Closets
Floor Auto scrubbers	Various
Mercury Spill Kits	On-site Stores, Areas where mercury is present

The house vacuum system is not designed for hazardous material cleanup, and SHALL NOT be used for that purpose.

#### **Eyewash and Shower Stations**

Emergency eyewash and safety showers are located throughout the facility for quick drenching or flushing of the eyes and body, if personnel are exposed to hazardous materials. As the standard (ANSI-Z358.1) states, an eyewash and/or safety shower should be installed within ten seconds or 55 feet from the hazard. Portable drenching stations are available for use as a temporary setup, in areas that do not meet the ten-second rule, until something permanent can be installed.

The facility has two portable safety showers and several portable eyewash systems, that can be used as needed. The portable eyewash and safety showers are located in room 1160 (Dungeon).

Additionally, zip lock bag containing a robe, slippers, and a pair of scissors will be available at each emergency drenching station, for use when individuals must disrobe during decontamination. These bags are labeled "Emergency Use Only"

### **Incompatibilities and Disposal Requirements**

It is imperative that all materials and equipment used to cleanup spills be evaluated to ensure compatibility with the spilled material. Determining the hazards associated with various chemicals requires training and experience. Safety Data Sheets (SDS) should be referenced for spill response, cleanup, and disposal requirements. The actual procedures for cleanup will depend upon many factors, including whether the spill is considered a "small" or "large" spill. Generally, a small spill is considered anything less than one (1) gallon. However, depending on the material spilled, even a small spill can create a serious emergency. All spilled material must be analyzed for corrosivity, reactivity, toxicity, and ignitability. Actual response procedures are developed based on this analysis.

Proper decontamination techniques are equally important during and after spill cleanup. The incident safety officer, a designated hazardous material specialist, or an area expert will determine decontamination techniques.

Proper disposal of all materials used during spill cleanup is important. Until complete characterization of the material can be accomplished, the spilled material, equipment, and supplies used during cleanup operations should be considered hazardous. Improper disposal of materials can result in personnel contamination, environmental damage, equipment and property damage, and severe fines for ON Semiconductor, as well as possible criminal and civil penalties for the individuals involved. When waste materials are generated during a spill cleanup, the Environmental Engineer must be consulted to ensure materials are properly characterized, contained, labeled, stored, and disposed. Minimizing the amount of absorbent material added to a spill, during cleanup, will help reduce the amount of material requiring disposal.

In the event of a spill at or near a floor or storm drains:

- Berm the drain to prevent the spilled material from entering the drain
- Contact the Environmental Engineer and Plant Operations
- Contain and confine the spill material
- Determine whether the spilled material can be allowed to enter a facility drain or if it needs to be cleaned up and packaged for off-site disposal

### **Specific ON Semiconductor Chemical Information**

The following matrix provides information about specific chemical properties, hazards, incompatibilities and basic cleanup techniques for chemicals stored/used at the ON Semiconductor Pocatello facility. Remember, a hazardous material specialist MUST be involved in determining proper cleanup techniques.

**CAUTION** – during spill cleanup this table shall only be used by persons competent to understand the content. Use of any equipment below must be approved, prior to use, by a designated Hazardous Material Specialist.

## ON Semiconductor Pocatello SPECIFIC CHEMICAL INFORMATION MATRIX

### ACIDS

CHEMICAL	PROPERTIES	INCOMPATIBILITIES	CLEAN-ROOM CLEANUP	NON-CLEANROOM CLEANUP	PERSONAL PROTECTIVE EQUIPMENT
HF 10:1 100:1 13:2 BOE 20:1 BOE	Clear, Colorless Liquid	Most metals, hydrogen sulfide, wood, paper, cotton and similar organic materials, alkalis, amines, ammonia gas, carbonates, cyanides, fluorine, phosphine, sulfides	Absorbent Wet Mop Wet Vacuum-	Lime Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Hydrochloric Acid, HCl	Clear, Yellow/White Liquid	Most metals, sulfuric acid, calcium carbide, rubber, some plastics	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Sulfuric Acid, H <sub>2</sub> SO <sub>4</sub>	Odorless, Colorless to Dark Brown Oily Liquid	Strong Oxidizers and Reducing Agents	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Phosphoric Acid, H <sub>3</sub> PO <sub>4</sub>	Clear to White	Organic Peroxides, Halogenated Organics, Alkalis, Chlorides, Amines, Ketones	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Hydrogen Peroxide, H <sub>2</sub> O <sub>2</sub>	Clear Colorless, Odorless, Slight Ozone Odor	Reducing Agents, Bases, Dirt, Wood, Paper, Essentially All Organic Material, Combustibles, Heavy Metals	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Acetic Acid	Clear, Colorless, Vinegar-Like Odor	Amines, Caustic Materials, Nitric Acid, Phosphorous Chlorides, Peroxides, Xylene, Ammonium Nitrate	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Nitric Acid, HNO <sub>3</sub>	Clear, White to Yellow	Metals, Reducing Agents, Alkalis, Carbides, Hydrogen Sulfide, Polyethylene, Combustibles	Absorbent Wet Mop Wet Vacuum	Soda Ash Absorbent Wet Mop Wet Vacuum	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed

### BASES

CHEMICAL	PROPERTIES	INCOMPATIBILITIES	CLEAN-ROOM CLEANUP	NON-CLEANROOM CLEANUP	PERSONAL PROTECTIVE EQUIPMENT
Ammonia	Colorless, Extremely Pungent Odor	Acids, Aldehydes, Calcium, Nitric Acid, Oxidizers, Arsine, Phosphine, Potassium Based Materials, Chlorine Based Materials, Vinyl Compounds	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Developer NMD-W LDD-26W	Colorless Liquid	Slightly Corrodes Metals	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed

Caustics	Various	Acids, Various	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, acid resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
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### ORGANICS

CHEMICAL	PROPERTIES	INCOMPATIBILITIES	CLEANROOM CLEANUP	NON-CLEANROOM CLEANUP	PERSONAL PROTECTIVE EQUIPMENT
Acetone	Colorless Liquid, Mint-Like, Sweet Odor	Oxidizing Agents, Organic Peroxides, Hydrogen Peroxide, Nitric Acid, Sulfuric Acid, Chloride, Bromine	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Isopropanol	Colorless, Transparent Liquid, Fragrant Odor	Strong Oxidizing Material	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Photoresist	Red Liquid, Mild Ester Odor	Oxidizing Agents, Bases, Acids	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Edge Bead Remover	Clear, Colorless, Sweet Odor	Strong Oxidizing Agents	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
R-11 Refrigerant	Volatile	Decomposes in Contact with Heat to Create Phosgene, Oxidizers, Acids, Bases	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed
Ethylene Glycol	Clear, Oily Liquid, Odorless	Strong Oxidizing Agents, Sulfuric Acid, Sodium Chloride, Potassium Dichromate, Oleum, Perchloric Acid	Absorbent Wet Mop	Absorbent Wet Mop	Safety glasses and/or chemical goggles, solvent resistant gloves, chemical protective suit, protective boots, respiratory protection as needed

NOTE: Absorbents used in the cleanroom are pig pillows/mats only - no particulates



**Appendix 3 - QUARTERLY ROUTINE STORMWATER INSPECTION FORM**

**Inspector's Name:** \_\_\_\_\_ **Date:** \_\_\_\_\_  
**Title:** \_\_\_\_\_ **Time:** \_\_\_\_\_  
**Weather Information:** \_\_\_\_\_

**LIST OF REQUIREMENTS (IF APPLICABLE)**

- No evidence of drips or leaks from pipes or valves
- Tanks and support systems are in good condition, not leaking or corroded.
- No leaking pumps and/or hose connections
- Dikes, walls or other physical barriers constructed to contain stormwater and segregate chemicals are all in good condition
- Area appears neat and orderly
- Adequate space in work areas
- No garbage or debris in area
- No evidence of dust from process operations
- Storm drains and catch basins are in good condition - free from debris and excessive silt

Area	Status		Corrective Action	Date Completed
	Acceptable	Not Acceptable		
Chemical Loading/Unloading Areas				
Roof Downspouts				
Employee Parking Area & Sidewalks				
Driveways				
Gas Pad				
Shipping and Receiving				
Material Roll-Off Bins				
Site Storm Drains and Catch Basins				
Perimeter Catch Basins				
Stormwater Detention Pond				
Spill Kits				
Emergency Generator Areas				
Grounds Equipment Building				
Waste Veranda (secondary containment)				
Snow Removal Equipment Storage				
Cooling Towers				
Landscape / Lawn Areas				
Adjoining SW Contributing Properties				

- No discoloration or residue from chemicals or oil drips and leaks

Inspector's Signature: \_\_\_\_\_



### Appendix 4 - QUARTERLY VISUAL ASSESSMENT FORM

**Inspector's Name:** \_\_\_\_\_ **Date:** \_\_\_\_\_  
**Title:** \_\_\_\_\_ **Time:** \_\_\_\_\_  
**Weather Information:** \_\_\_\_\_

This sample needs to be taken at the outfall, i.e. the pond overflow drain. If the water is not running out the overflow, the sample does not need to be taken.

Sample Location: \_\_\_\_\_

Nature of the discharge (i.e., runoff or snowmelt): \_\_\_\_\_

Sample taken within first 30 minutes of storm event? \_\_\_\_yes \_\_\_\_ no

If no, why not

\_\_\_\_\_  
 \_\_\_\_\_  
 \_\_\_\_\_

Characteristic	Status		Probable Source of Contamination
	Acceptable	Not Acceptable	
Color			
Odor			
Clarity			
Floating Solid			
Settled Solids			
Suspended Solids			
Foam			
Oil Sheen			
Other indicators of stormwater pollution			

Comments: \_\_\_\_\_  
 \_\_\_\_\_  
 \_\_\_\_\_

Inspector's Signature: \_\_\_\_\_

# Appendix 5 – Documentation Regarding Endangered and Threatened Species and Critical Habitat Protection

Multi-Sector General Permit (MSGP)

## Criterion A Eligibility Requirements

In order to be eligible for coverage under criterion A, you must confirm that the following is true:

I have confirmed there to be no listed species and no critical habitat in my action area.

- **If the above is true, you may select criterion A on your NOI form.** You must also provide a description of the basis for the criterion selected on your NOI form. You must include this completed worksheet in your SWPPP. *Note: If your Official Species List from the USFWS indicated no species or critical habitat were present in your action area, include the full consultation tracking code at the top of your Official Species List in your NOI submittal in the question "Provide a brief summary of the basis for the criterion selected in Appendix E." If an Official Species List was not available on IPaC, list the contact date and name of the Service staff with whom you corresponded to verify no USFWS species or critical habitat were present in your action area.*
- If the above is not true, you may not select criterion A and must proceed to [Step 4](#) to determine if you can become eligible under criterion C.

**Note:** For existing dischargers that have previously obtained coverage under criterion A, you must verify whether listed species and/or critical habitat are expected to exist in your action area, as described above. Please note that if you now find that your action area overlaps with listed species or critical habitat, you must proceed to [Step 4](#).



## United States Department of the Interior



FISH AND WILDLIFE SERVICE  
Idaho Fish and Wildlife Office  
1387 SOUTH VINNELL WAY, SUITE 368  
BOISE, ID 83709  
PHONE: (208)378-5243 FAX: (208)378-5262

Consultation Code: 01EIFW00-2015-SLI-0790  
Event Code: 01EIFW00-2015-E-00865  
Project Name: ON Semiconductor

September 10, 2015

Subject: List of threatened and endangered species that may occur in your proposed project location, and/or may be affected by your proposed project

To Whom It May Concern:

The enclosed species list identifies threatened, endangered, proposed and candidate species, as well as proposed and final designated critical habitat, that may occur within the boundary of your proposed project and/or may be affected by your proposed project. The species list fulfills the requirements of the U.S. Fish and Wildlife Service (Service) under section 7(c) of the Endangered Species Act (Act) of 1973, as amended (16 U.S.C. 1531 *et seq.*).

New information based on updated surveys, changes in the abundance and distribution of species, changed habitat conditions, or other factors could change this list. Please feel free to contact us if you need more current information or assistance regarding the potential impacts to federally proposed, listed, and candidate species and federally designated and proposed critical habitat. Please note that under 50 CFR 402.12(e) of the regulations implementing section 7 of the Act, the accuracy of this species list should be verified after 90 days. This verification can be completed formally or informally as desired. The Service recommends that verification be completed by visiting the ECOS-IPaC website at regular intervals during project planning and implementation for updates to species lists and information. An updated list may be requested through the ECOS-IPaC system by completing the same process used to receive the enclosed list.

The purpose of the Act is to provide a means whereby threatened and endangered species and the ecosystems upon which they depend may be conserved. Under sections 7(a)(1) and 7(a)(2) of the Act and its implementing regulations (50 CFR 402 *et seq.*), Federal agencies are required to utilize their authorities to carry out programs for the conservation of threatened and endangered species and to determine whether projects may affect threatened and endangered species and/or designated critical habitat.

A Biological Assessment is required for construction projects (or other undertakings having similar physical impacts) that are major Federal actions significantly affecting the quality of the human environment as defined in the National Environmental Policy Act (42 U.S.C. 4332(2) (c)). For projects other than major construction activities, the Service suggests that a biological evaluation similar to a Biological Assessment be prepared to determine whether the project may affect listed or proposed species and/or designated or proposed critical habitat. Recommended contents of a Biological Assessment are described at 50 CFR 402.12.

If a Federal agency determines, based on the Biological Assessment or biological evaluation, that listed species and/or designated critical habitat may be affected by the proposed project, the agency is required to consult with the Service pursuant to 50 CFR 402. In addition, the Service recommends that candidate species, proposed species and proposed critical habitat be addressed within the consultation. More information on the regulations and procedures for section 7 consultation, including the role of permit or license applicants, can be found in the "Endangered Species Consultation Handbook" at:

<http://www.fws.gov/endangered/esa-library/pdf/TOC-GLOS.PDF>

Please be aware that bald and golden eagles are protected under the Bald and Golden Eagle Protection Act (16 U.S.C. 668 *et seq.*), and projects affecting these species may require development of an eagle conservation plan ([http://www.fws.gov/windenergy/eagle\\_guidance.html](http://www.fws.gov/windenergy/eagle_guidance.html)). Additionally, wind energy projects should follow the wind energy guidelines (<http://www.fws.gov/windenergy/>) for minimizing impacts to migratory birds and bats.

Guidance for minimizing impacts to migratory birds for projects including communications towers (e.g., cellular, digital television, radio, and emergency broadcast) can be found at: <http://www.fws.gov/migratorybirds/CurrentBirdIssues/Hazards/towers/towers.htm>; <http://www.towerkill.com>; and <http://www.fws.gov/migratorybirds/CurrentBirdIssues/Hazards/towers/comtow.html>.

Please note the module for identifying proposed and designated critical habitat by your defined project area is currently incomplete. At this time, we ask that you use the following County by County list to aid you in determining whether your project may affect proposed or designated critical habitat in your action area.

**Canada Lynx (*Lynx canadensis*)**

Designated Critical Habitat: (designated February 24, 2009) Boundary County.

Federal Register Notice:

<http://www.gpo.gov/fdsys/pkg/FR-2009-02-25/pdf/E9-3512.pdf#page=1>

Printable Maps:

[http://www.fws.gov/mountain-](http://www.fws.gov/mountain-prairie/species/mammals/lynx/criticalhabitat_files/20081222_fedreg_unit3_draft)

[prairie/species/mammals/lynx/criticalhabitat\\_files/20081222\\_fedreg\\_unit3\\_draft](http://www.fws.gov/mountain-prairie/species/mammals/lynx/criticalhabitat_files/20081222_fedreg_unit3_draft).GIS Data:

[http://criticalhabitat.fws.gov/docs/crithab/zip/lunx\\_ch.zip](http://criticalhabitat.fws.gov/docs/crithab/zip/lunx_ch.zip)

KML for Google Earth: (None Currently Available)

**Selkirk Mountains Woodland Caribou (*Rangifer tarandus Caribou*)**

Proposed Critical Habitat: (proposed Noveber 30, 2011) Bonner and Boundary Counties.

Federal Register Notice: <http://www.fws.gov/idaho/home/2011-30451FINALR.pdf>

Printable Maps: [http://www.fws.gov/idaho/home/Map1\\_sub1\\_150.pdf](http://www.fws.gov/idaho/home/Map1_sub1_150.pdf)

GIS Data: (None Currently Available)

KML for Google Earth: (None Currently Available)

**Bull Trout (*Salvelinus confluentus*)**

Designated Critical Habitat: (designated September 30, 2010) Adams, Benewah, Blaine, Boise, Bonner, Boundary, Butte, Camas, Clearwater, Custer, Elmore, Gem, Idaho, Kootenai, Lemhi, Lewis, Nez Perce, Owyhee, Shoshone, Valley, and Washington Counties.

Federal Register Notice:

<http://www.gpo.gov/fdsys/pkg/FR-2010-10-18/pdf/2010-25028.pdf#page=2>

Printable Maps: [http://www.fws.gov/pacific/bulltrout/CH2010\\_Maps.cfm#CHMaps](http://www.fws.gov/pacific/bulltrout/CH2010_Maps.cfm#CHMaps)

GIS Data: <http://criticalhabitat.fws.gov/docs/crithab/zip/bulltrout.zip>

KML for Google Earth:

[http://www.fws.gov/pacific/bulltrout/finalcrithab/BT\\_FCH\\_2010\\_KML.zip](http://www.fws.gov/pacific/bulltrout/finalcrithab/BT_FCH_2010_KML.zip)

**Kootenai River White Sturgeon (*Acipenser transmontanus*)**

Designated Critical Habitat: (designated July 9, 2008) Boundary County.

Federal Register Notice:

<http://www.gpo.gov/fdsys/pkg/FR-2008-07-09/pdf/E8-15134.pdf#page=1>

Printable Maps: (None Currently Available)

GIS Data: [http://criticalhabitat.fws.gov/docs/crithab/zip/fch\\_73fr39506\\_acit\\_2009.zip](http://criticalhabitat.fws.gov/docs/crithab/zip/fch_73fr39506_acit_2009.zip)

KML for Google Earth: (None Currently Available)

**Slickspot Peppergrass (*Lepidium papilliferum*)**

Proposed Critical Habitat: Ada, Canyon, Elmore, Gem, Owyhee, and Payette Counties.

Federal Register Notice: <http://www.gpo.gov/fdsys/pkg/FR-2011-10-26/pdf/2011-27727.pdf>

Printable Maps: <http://www.fws.gov/idaho/Lepidium.html>

GIS Data: (None Currently Available)

KML for Google Earth: (None Currently Available)

We appreciate your concern for threatened and endangered species. The Service encourages Federal agencies to include conservation of threatened and endangered species into their project

planning to further the purposes of the Act. Please include the Consultation Tracking Number in the header of this letter with any request for consultation or correspondence about your project that you submit to our office.

Attachment

## Official Species List

**Provided by:**

Idaho Fish and Wildlife Office  
1387 SOUTH VINNELL WAY, SUITE 368  
BOISE, ID 83709  
(208) 378-5243

**Consultation Code:** 01EIFW00-2015-SLI-0790

**Event Code:** 01EIFW00-2015-E-00865

**Project Type:** WATER QUALITY MODIFICATION

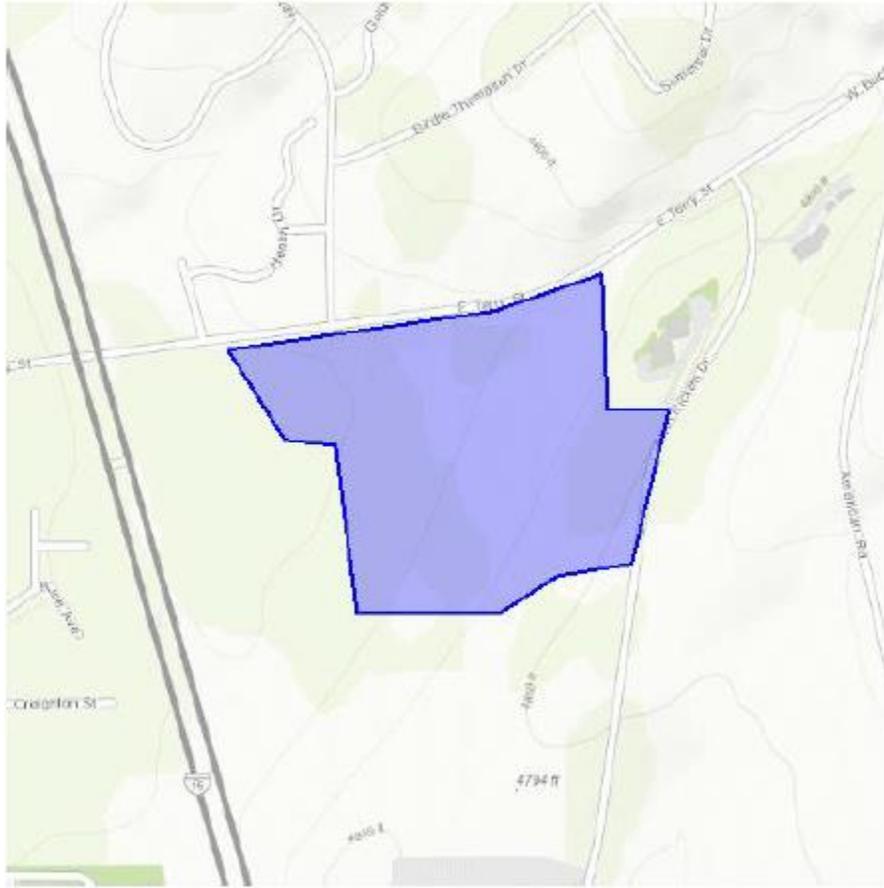
**Project Name:** ON Semiconductor

**Project Description:** Storm water - Official Species List Request for MSGP

**Please Note:** The FWS office may have modified the Project Name and/or Project Description, so it may be different from what was submitted in your previous request. If the Consultation Code matches, the FWS considers this to be the same project. Contact the office in the 'Provided by' section of your previous Official Species list if you have any questions or concerns.

United States Department of Interior  
Fish and Wildlife Service  
Project name: ON Semiconductor

**Project Location Map:**



**Project Coordinates:** MULTIPOLYGON (((-112.4126672744751 42.868085478946924, -112.41258144378662 42.866402688514626, -112.41156220436095 42.86641055212799, -112.41218447685242 42.86452325618831, -112.41342902183533 42.864373842795025, -112.41438388824461 42.86392560044545, -112.41677641868591 42.86392560044545, -112.41714119911192 42.865978051904726, -112.41798877716063 42.86604882487589, -112.41894364356995 42.867149727312686, -112.41449117660522 42.86761367317331, -112.4126672744751 42.868085478946924)))

**Project Counties:** Bannock, ID



United States Department of Interior  
Fish and Wildlife Service

Project name: ON Semiconductor

## Endangered Species Act Species List

There are a total of 0 threatened or endangered species on your species list. Species on this list should be considered in an effects analysis for your project and could include species that exist in another geographic area. For example, certain fish may appear on the species list because a project could affect downstream species. Critical habitats listed under the **Has Critical Habitat** column may or may not lie within your project area. See the **Critical habitats within your project area** section further below for critical habitat that lies within your project. Please contact the designated FWS office if you have questions.

There are no listed species identified for the vicinity of your project.



United States Department of Interior  
Fish and Wildlife Service

Project name: ON Semiconductor

## Critical habitats that lie within your project area

There are no critical habitats within your project area.

**Step One: Are you an existing facility that is reapplying for certification under the 2015 MSGP?**

If you are an existing facility you should have already addressed NHPA issues. To gain coverage under the 2008 MSGP you were required to certify that you were either not affecting historic properties or had obtained written agreement from the relevant SHPO or THPO regarding methods of mitigating potential impacts. As long as you are not constructing or installing any new stormwater control measures then you have met eligibility Criterion A of the MSGP. After you submit your NOI, there is a 30-day waiting period during which the SHPO, THPO, or other tribal representative may review your NOI. The SHPO, THPO, or other tribal representative may request that EPA hold up authorization based on concerns about potential adverse impacts to historic properties. EPA will evaluate any such request and notify you if any additional measures to address adverse impacts to historic properties are necessary.

As an existing facility that gained coverage under the 2008 MSGP, ON Semiconductor Pocatello has certified that it has not affected historic properties, and because this facility is not constructing or installing any new stormwater control measures, it has met eligibility Criterion A of the 2015 MSGP.